



Example of using Cu core balls (page 34)



DEPARTMENTS

	AEI NEWS	8
	IN VIEW THIS MONTH	10
	BUSINESS STRATEGY	65
	COMPANY ON THE MOVE	66
	PRODUCT NEWS	68

ASIA ELECTRONICS INDUSTRY (ISSN 1342-422X) is published monthly by Dempa Publications, Inc., 1-11-15 Higashi Gotanda, Shinagawa-ku, Tokyo 141-8715, Japan Tel: +81-3-3445-6111 Fax: +81-3-3445-6890. Editorial e-mail: may@dempa.co.jp;

Subscription e-mail: circulationmanila@dempa.co.jp. The magazine is distributed free to qualified subscribers in ASEAN countries (Thailand, Indonesia, The Philippines, Malaysia, Singapore, Brunei, Vietnam, Myanmar, Cambodia and Laos), as well as Korea, Taiwan and Hong Kong.

Paid air mail subscription is available to non-qualified subscribers in the Asian and Pacific regions for US\$150 per year and US\$260 for two years. For other areas, air mail subscription fees are US\$160 per year and US\$280 for two years. Paid subscription is accepted at <http://aei.dempa.net/paidsub/subscription.html>

Send address corrections to Dempa Publications, Inc., c/o Quantum Solutions (HK) Ltd. Unit 3-6, G/F Pacific Trade Centre, 2 Kai Hing Road, Kowloon Bay, Kowloon, Hong Kong

TAIWAN: International Dempa Trade Co. Ltd., 7F, No. 34, Sec. 1, Nanjing East Road., Taipei, Taiwan 104 Tel: +886-2-2563 4595 Fax: +886-2-2567-5559 **KOREA:** Dempa Publications, Room 1019, Punglim VIP Tel, 404, Gongdeuk-dong, Mapo, Seoul, Korea 04144, Tel: +82-2-714-2983 Fax: +82-2-714-2984 **PHILIPPINES:** Dempa Publications, Inc. - Regional Headquarters, Herrera Tower, Room 2510, 98 V.A. Rufino Street, Salcedo Village, Makati City, Philippines, Tel: +63-2-845-0906 Fax: +63-2-845-1829

President & Publisher: Tsutomu Hirayama
Copyright © 2018 by Dempa Publications, Inc.

All rights reserved. The contents of this magazine may not be reproduced in whole or in part without the prior permission of the copyright owner. Printed in China.

ZOOM-IN

R&D Leader imec Starts Integrated Development Service _____ 12

SHOW PREVIEW

TAITRONICS and AIoT Taiwan _____ 14

NEPCON SOUTH CHINA 2018

ASM _____ 16
FUJI _____ 18
Yamaha Motor _____ 20
JUKI _____ 22
Tokyo Weld _____ 24
Japan Unix _____ 26
Panasonic _____ 32
SMIC _____ 34

SPECIAL REPORT

Players Chart Advances in Industrial Wireless Technologies _____ 36
Novel Systems to Propel Growth of Electronic Parts, Materials _____ 38
New Technologies Support Electronic Circuit Innovation _____ 41

COMPONENT MATERIALS

_____ 43
SMT's: IN REVIEW _____ 45

TECHNOLOGY HIGHLIGHT

Ultra-Thin Full-Color Tactile Glove Features Three Touch Senses _____ 51

PRODUCT HIGHLIGHT

Highly Integrated PMIC Bolsters Seamless Connectivity in IoT Era _____ 52
Cutting-Edge FPGA Module Suits Universal Boards _____ 54
JAE's ECU Connector Meets Safety, Environment Regulations _____ 55
TDK's Novel Sensors Aid Safety-Critical Applications _____ 56

SHOW REPORT

SID 2018 _____ 58
ConnecTech Asia 2018 _____ 61

INDUSTRY REPORT

High-Density Packaging Accelerates in Semiconductor Devices _____ 63
Power Inductors for Automobiles Race for Reliability _____ 64